Amendments to the Specification:

After the paragraph beginning on page 5, line 1, of the original specification, please add the following new paragraphs:

FIG. 6 is a flow diagram of a die bonding method according to one embodiment.

FIG. 7 is a block diagram of a laser machining system according to one embodiment for use in a die bonding apparatus.

Please replace the paragraph beginning on page 5, line 9, of the original specification with the following amended paragraph:

The carrier base 13 may be, for example, any known carrier film as used in industry, a substantially inflexible support used in thin film dicing or backgrinding or a glass or other transparent solid. Alternatively, the carrier base may be an inflexible transparent backgrinding tape with the wafer mounted facedown on the backgrinding tape for dicing after a backgrinding process. To dice structure 10, a laser machining system 700 is provided as shown in block diagram form in FIG. 7. System 700 includes a laser source 702 for producing laser beam 31, 32, 33 and a laser scanner 704 to allow laser beam 31, 32, 33 to reach various parts of structure 10 to form dice lanes. System 700 also includes a laser controller 706 for controlling machining parameters of laser beam 31, 32, 33. Laser controller 706 operates according to cutting strategies or machining profiles stored in a memory 708 of apparatus 700.

Please replace the paragraph beginning on page 6, line 5, of the original specification with the following amended paragraph:

A known translation table may be provided as part of laser scanner 704 to allow access of the laser beam to all parts of the wafer to be machined.

Please replace the paragraph beginning on page 6, line 26, of the original specification with the following amended paragraph:

FIG. 6 is a flow diagram of a die bonding method 600 according to one embodiment. Once the structure has been machined (step 602), die bonding of a singulated die proceeds substantially as in the prior art. The carrier base 13, or an adhesive, not shown, between the carrier base, tape or film and the adhesive layer, is cured with ultraviolet light to release the singulated die 15 from the carrier tape or film 13 (step 604). The singulated die 15 is picked from the carrier base, tape or film 13 (step 606) and placed on a die pad (step 608). Alternatively, the die 15 may be picked and placed on another die to form a multi-stack die package. The adhesive layer on the singulated die 15 is heat cured to adhere the singulated die to the die pad (step 610), or another die, for further known processing.